

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	9	("6090473" "6229085" "6262364"). PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/05 14:58
S2	0	S1 and (electrolysis electrolytic electrochemic\$4 electrodeposit\$5 electroplat\$5)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/05 15:50
S3	1041	(electrolysis electrolytic electrochemic\$4 electrodeposit\$5 electroplat\$5) and electromagnetic near5 shield	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/05 15:50
S4	92	(electrolysis electrolytic electrochemic\$4 electrodeposit\$5 electroplat\$5) and electromagnetic near5 (filter shield\$3) and plasma near5 panel	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/05 15:52
S5	86	(electrolytic electrochemic\$4 electrodeposit\$5 electroplat\$5) and electromagnetic near5 (filter shield\$3) and plasma near5 panel	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/05 17:12
S6	2	("205"/\$.ccls. "204"/\$.ccls.) and (electrolytic electrochemic\$4 electrodeposit\$5 electroplat\$5) and electromagnetic near5 (filter shield\$3) and plasma near5 panel	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/05 17:27
S7	17	(electrolytic electrochemic\$4 electrodeposit\$5 electroplat\$5) same adhesive and electromagnetic near5 (filter shield\$3) and plasma near5 panel	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/05 16:39
S8	11	((plating electrolytic electrochemic\$4 electrodeposit\$5 electroplat\$5) near5 layer) same adher\$3 and electromagnetic near5 (filter shield\$3) and plasma near5 panel	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/05 17:09

S9	16	((plating electrolytic electrochemic\$4 electrodeposit\$5 electroplat\$5) near\$5 layer) same (bond\$4 adher\$3) and electromagnetic near\$5 (filter shield\$3) and plasma near\$5 panel	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/05 17:10
S10	254	("205"/\$.ccls. "204"/\$.ccls.) and (electroform\$3 electrolytic electrochemic\$4 electrodeposit\$5 electroplat\$5) with peel\$3 and pattern\$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/05 17:31
S11	16	("205"/\$.ccls. "204"/\$.ccls.) and (electroform\$3 electrolytic electrochemic\$4 electrodeposit\$5 electroplat\$5) with peel\$3 and pattern\$3 same mold	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/05 17:34
S12	4	("205"/\$.ccls. "204"/\$.ccls.) and (electroform\$3 electrolytic electrochemic\$4 electrodeposit\$5 electroplat\$5) and (peel\$3 with (pattern\$3 same mold))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/05 17:35
S13	14	("205"/\$.ccls. "204"/\$.ccls.) and (electroform\$3 electrolytic electrochemic\$4 electrodeposit\$5 electroplat\$5) and (peel\$3 same (pattern\$3 same mold))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/05 17:46
S14	14	("205"/\$.ccls. "204"/\$.ccls.) and (electroform\$3 electrolytic electrochemic\$4 electrodeposit\$5 electroplat\$5) and (peel\$3 same adhesive and (pattern\$3 same mold))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/05 17:48
S15	223	(electroform\$3 electrolytic electrochemic\$4 electrodeposit\$5 electroplat\$5) and (peel\$3 same adhesive and (pattern\$3 same mold))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/05 17:49
S16	9	(electroform\$3 electrolytic electrochemic\$4 electrodeposit\$5 electroplat\$5) and (peel\$3 same adhesive and (pattern\$3 same mold)) and plasma near\$5 panel	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/06 10:51

S17	0	205/50-80.ccls. and (electroform\$3 electrolytic electrochemic\$4 electrodeposit\$5 electroplat\$5) and (peel\$3 same adhesive and (pattern\$3 same (die mold))) and plasma near5 panel	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/06 10:53
S18	9	205/50-80.ccls. and (electroform\$3 electrolytic electrochemic\$4 electrodeposit\$5 electroplat\$5) and (peel\$3 same adhesive and (pattern\$3 same (die mold)))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/06 10:54
S19	61	205/50-80.ccls. and (electroform\$3 electrolytic electrochemic\$4 electrodeposit\$5 electroplat\$5) and ((remov\$3 lift peel\$3) same adhesive and (pattern\$3 same (mask\$3 \$5resist)))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/06 12:41
S20	0	205/50-80.ccls. and (electroform\$3 electrolytic electrochemic\$4 electrodeposit\$5 electroplat\$5) and ((remov\$3 lift peel\$3) same (tacky sticky adhesive) and (pattern\$3 same (mask\$3 \$5resist))) not S19	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/06 12:42
S21	2	205/50-80.ccls. and (electroform\$3 electrolytic electrochemic\$4 electrodeposit\$5 electroplat\$5) and ((remov\$3 lift peel\$3) same (adhesive) and (oxide same (mask\$3 \$5resist))) not S19	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/06 12:43
S22	12	205/50-80.ccls. and (electroform\$3 electrolytic electrochemic\$4 electrodeposit\$5 electroplat\$5) and ((remov\$3 lift peel\$3) same (adhesive) and (oxide same (mask\$3 \$5resist)))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/06 12:45
S23	0	205/50-80.ccls. and (electroform\$3 electrolytic electrochemic\$4 electrodeposit\$5 electroplat\$5) and ((remov\$3 lift peel\$3) same (adhesive) and (oxide near10 (mask\$3)))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/06 12:46
S24	9	205/50-80.ccls. and (electroform\$3 electrolytic electrochemic\$4 electrodeposit\$5 electroplat\$5) and (oxide near10 (mask\$3))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/06 12:48

S25	226	"205"/\$.ccls. and (electroform\$3 electrolytic electrochemic\$4 electrodeposit\$5 electroplat\$5) and (oxide near10 (mask\$3))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/06 12:49
S26	94	"205"/\$.ccls. and (electroform\$3 electroplat\$5) and (oxide near10 (mask\$3))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/06 12:51
S27	35	"205"/\$.ccls. and (electroform\$3 electroplat\$5) and (oxide near10 (mask\$3)) with \$5resist	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/06 13:22
S28	4	"205"/\$.ccls. and (electroform\$3) and (oxide near10 (mask\$3)) with \$5resist	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/06 13:21
S29	62	(electroform\$3) and (oxide near10 (mask\$3)) with \$5resist	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/06 13:21
S30	5	"205"/\$.ccls. and (electroform\$3) and (oxide near10 (mask\$3))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/06 13:22
S31	43	("204"/\$.ccls. "205"/\$.ccls.) and (electroform\$3 electroplat\$5) and (oxide near10 (mask\$3)) with \$5resist	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/06 13:23